

February 2008

74LVX125 Low Voltage Quad Buffer with 3-STATE Outputs

Features

- Input voltage level translation from 5V to 3V
- Ideal for low power/low noise 3.3V applications
- Guaranteed simultaneous switching noise level and dynamic threshold performance

General Description

The LVX125 contains four independent non-inverting buffers with 3-STATE outputs. The inputs tolerate voltages up to 7V allowing the interface of 5V systems to 3V systems.

Ordering Information

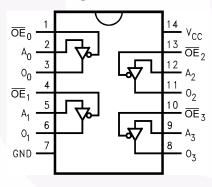
Order Number	Package Number	Package Description
74LVX125M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LVX125SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVX125MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

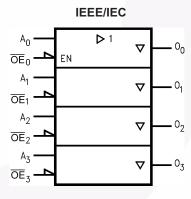


All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



Logic Symbol



Pin Description

Pin Names	Description
A _n	Inputs
ŌĒn	Output Enable Inputs
O _n	Outputs

Truth Table

Inp	Output	
ŌĒn	A _n	O _n
L	L	L
L	Н	Н
Н	Х	Z

H = HIGH Voltage Level

L = LOW Voltage Level

Z = High Impedance

X = Immaterial

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
I _{IK}	DC Input Diode Current, V _I = -0.5V	–20mA
VI	DC Input Voltage	-0.5V to 7V
I _{OK}	DC Output Diode Current	
	$V_{O} = -0.5V$	–20mA
	$V_{O} = V_{CC} + 0.5V$	+20mA
V _O	DC Output Voltage	-0.5V to V _{CC} + 0.5V
Io	DC Output Source or Sink Current	±25mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current	±50mA
T _{STG}	Storage Temperature	−65°C to +150°C
Р	Power Dissipation	180mW

Recommended Operating Conditions⁽¹⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	2.0V to 3.6V
V _I	Input Voltage	0V to 5.5V
Vo	Output Voltage	0V to V _{CC}
T _A	Operating Temperature	–40°C to +85°C
Δt / ΔV	Input Rise and Fall Time	0ns/V to 100ns/V

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

				T	λ = +2 5	°C		40°C to 5°C	
Symbol	Parameter	V _{CC}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units
V _{IH}	HIGH Level Input	2.0		1.5			1.5		V
	Voltage	3.0		2.0			2.0		
		3.6		2.4			2.4		
V _{IL}	LOW Level Input	2.0				0.5		0.5	V
	Voltage	3.0				0.8		0.8	
		3.6				0.8		0.8	
V _{OH}	HIGH Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50\mu\text{A}$	1.9	2.0		1.9		V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -50\mu\text{A}$	2.9	3.0		2.9		
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -4\text{mA}$	2.58			2.48		
V _{OL}	LOW Level Output Voltage	2.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 50 \mu A$		0.0	0.1		0.1	V
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 50 \mu A$		0.0	0.1		0.1	
			$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 4\text{mA}$			0.36		0.44	
l _{OZ}	3-STATE Output Off-State Current	3.6	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $V_{OUT} = V_{CC} \text{ or GND}$			±0.25		±2.5	μA
I _{IN}	Input Leakage Current	3.6	V _{IN} = 5.5V or GND			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	3.6	$V_{IN} = V_{CC}$ or GND			4.0		40.0	μA

Noise Characteristics⁽²⁾

				$T_A = 25^{\circ}C$		
Symbol	Parameter	V _{CC} (V)	C _L (pF)	Тур.	Limit	Units
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3	50	0.3	0.8	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3	50	-0.3	-0.8	V
V _{IHD}	Minimum HIGH Level Dynamic Input Voltage	3.3	50		2.0	V
V _{ILD}	Maximum LOW Level Dynamic Input Voltage	3.3	50		0.8	V

Note:

2. Input $t_r = t_f = 3ns$

AC Electrical Characteristics

				T	\ = +25	°C	T _A = -		
Symbol	Parameter	V _{CC} (V)	Conditions	Min.	Тур.	Max.	Min.	Max.	Units
t _{PLH} , t _{PHL}	Propagation Delay	2.7	C _L = 15pF		5.8	10.1	1.0	13.5	ns
	Time, Data to Output		$C_L = 50pF$		8.3	13.6	1.0	17.0	
	Output	3.3 ± 0.3	C _L = 15pF		4.4	6.2	1.0	8.5	
			$C_L = 50pF$		6.9	9.7	1.0	12.0	
t _{PZH} , t _{PZL}	Output Enable Time	2.7	$C_L = 15pF, R_L = 1k\Omega$		5.3	9.3	1.0	12.5	ns
			$C_L = 50 pF, R_L = 1 k\Omega$		7.8	12.8	1.0	16.0	
		3.3 ± 0.3	$C_L = 15pF, R_L = 1k\Omega$		4.0	5.6	1.0	7.5	
			$C_L = 50 pF, R_L = 1 k\Omega$		6.5	9.1	1.0	11.0	
t _{PHZ} , t _{PLZ}	Output Disable	2.7	$C_L = 50 pF, R_L = 1 k\Omega$		10.0	15.7	1.0	19.0	ns
	Time	3.3 ± 0.3	$C_L = 50 pF, R_L = 1 k\Omega$		8.3	11.2	1.0	13.0	
toshl, toshh	Output to Output	2.7	$C_L = 50pF$			1.5		1.5	ns
	Skew ⁽³⁾	3.3				1.5		1.5	

Note

3. Parameter guaranteed by design $t_{OSLH} = |t_{PLHm} - t_{PLHn}|$, $t_{OSHL} = |t_{PHLm} - t_{PHLn}|$

Capacitance

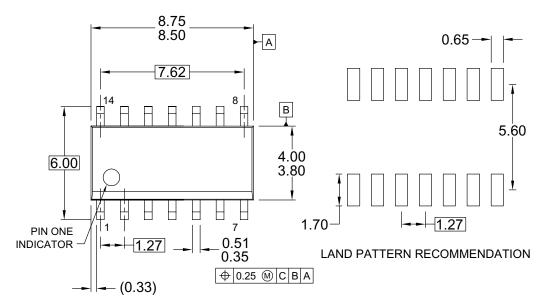
		1	T _A = +25°	С	T _A = -4	I0°C to	
Symbol	Parameter	Min.	Тур.	Max.	Min.	Max.	Units
C _{IN}	Input Capacitance		4	10		10	pF
C _{PD}	Power Dissipation Capacitance ⁽⁴⁾		14				pF

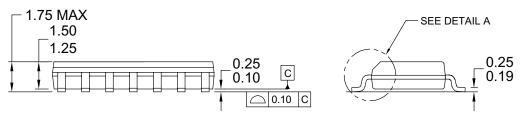
Note:

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation: $I_{CC(opr.)} = \frac{C_{PD} \times V_{CC} \times f_{IN} \times I_{CC}}{4 \text{ (per bit)}}$

Physical Dimensions





NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC

- MS-012, VARIATION AB, ISSUE C, 0.50 X 45° ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 DIMENSIONS DO NOT INCLUDE MOLD R0.10 **GAGE PLANE** FLASH OR BURRS. R0.10
- 0.36 0.90 SEATING PLANE 0.50 (1.04)

DETAIL A SCALE: 20:1

- LANDPATTERN STANDARD: SOIC127P600X145-14M
- DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

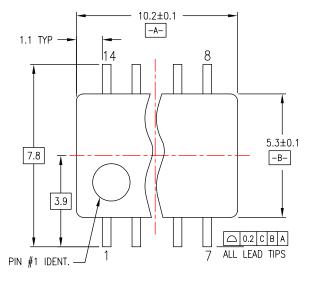
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

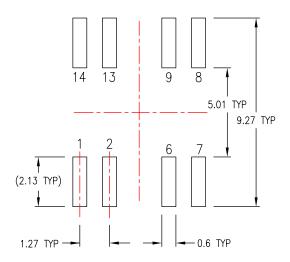
Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

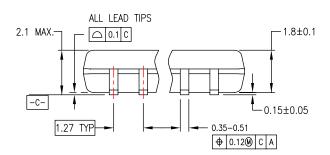
http://www.fairchildsemi.com/packaging/

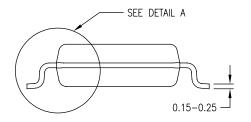
Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATION



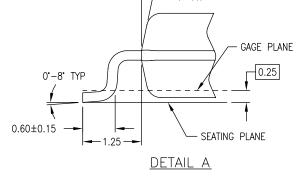


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.

- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

http://www.fairchildsemi.com/packaging/

Physical Dimensions (Continued) 5.0±0.1 -A-0.43 TYF 0.65 6.4 4.4±0.1 -B--1.65 3.2 □ 0.2 C B A PIN #1 IDENT. 6 10 LAND PATTERN RECOMMENDATION SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX □ 0.1 C -0.10 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30⊕ 0.13M ABS CS 12.00°TOP & BOTTOM R0.09 min **GAGE PLANE** 0.25 0°-8° NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153. 0.6±0.1 SEATING PLANE R0.09min VARIATION AB, REF NOTE 6 1 00 **B. DIMENSIONS ARE IN MILLIMETERS** DETAIL A

- B. DIMENSIONS ARE IN MILLIMETERSC. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/packaging/





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

ACEx®
Build it Now™
CorePLUS™
CROSSVOLT™
CTL™

Current Transfer Logic™ EcoSPARK[®] EZSWITCH™ *

EZ™ **F**®

Fairchild[®]
Fairchild Semiconductor[®]
FACT Quiet Series[™]

FACT[®]
FAST[®]
FastvCore[™]
FlashWriter[®]*

FPS™ FRFET®

Global Power Resource^{sм}

Green FPS™

Green FPS™e-Series™

GTO™ *i-Lo™*IntelliMAX™
ISOPLANAR™
MegaBuck™

MICROCOUPLER™
MicroFET™
MicroPak™
MillerDrive™
Motion-SPM™

OPTOLOGIC[®]
OPTOPLANAR[®]

PDP-SPM™ Power220® POWEREDGE® Power-SPM™ PowerTrench®

Programmable Active Droop™

QFE1 QS™

QT Optoelectronics™
Quiet Series™
RapidConfigure™
SMART START™
SPM®
STEALTH™
SuperFET™
SuperSOT™3
SuperSOT™6

SuperSOT™8

The Power Franchise®

P Wer'
franchise
TinyBoost™
TinyBuck™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyPWM™
TinyWire™
µSerDes™
UHC®

SupreMOS™

SyncFET™
SYSTEM®
GENERAL

Ultra FRFET™ UniFET™ VCX™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. I33

^{*} EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.